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POLYAMIDE RESIN COMPOSITION AND ITS PRODUCTION

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Abstract

PURPOSE: To obtain a composition, having a high strength and rigidity, excellent in ductility, good in molding appearance and excellent in gas barrier properties.

CONSTITUTION: This polyamide resin composition comprises an intercalation compound containing a phyllosilicate having $>=30$ mequiv./100g cation exchange capacity as a host and a quaternary ammonium ion having a $>=12$ C alkyl group as a guest in an amount of 1-20wt.% expressed in terms of inorganic ash content and a polyamide resin having 70-500 number-average polymerization degree. Furthermore, this method for producing the resin composition is provided and a polyamide-based resin composition comprises the polyamide resin and an acid-modified polyolefin resin.

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